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Passion for Technology

## European LVDS Octal Repeater

TEC-ED & TEC-SW Final Presentation Days

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# ABOUT ARQUIMEA

**ARQUIMEA** and **ARQUIMEA DEUTSCHLAND** are Sister Companies with complementary capabilities

Fabless Design Houses specialized in **hi-rel technologies** for **space applications**

Suppliers of **electronics, microelectronics and mechanisms**

Strong **R&D** activity and **product-oriented** strategy

 EUR 6.5M revenues in FY17

 34 employees



# ABOUT ARQUIMEA

## Customers and Partners

ITAR free

Fabless

Design house

Space & hi-rel

Multinational

### MEMBER OF



### BUSINESS AREAS

- ELECTRONICS & MICROELECTRONICS
- ACTUATORS & MECHANISMS
- NUCLEAR WASTE DISPOSAL TECHNOLOGIES

### MAIN COSTUMERS & PARTNERS



中国空间技术研究院  
China Academy of Space Technology



# ABOUT ARQUIMEA

## Microelectronics – General Capabilities

### SPACE APPLICATIONS

**Space-qualified** electronic systems and components

1500+ flight chips delivered to date

Turnkey projects: **ASIC, FPGA** and electronic systems

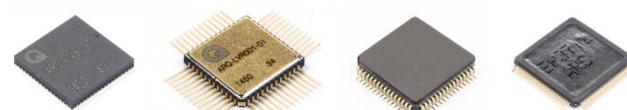
Analog, Digital and Mixed-Signal

Low power, low frequency, high voltage

Technology characterization

Design Centers in **Spain** and **Germany**

Main customers:



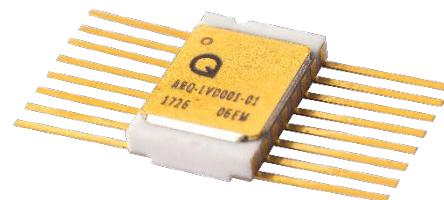
### PRODUCTS

#### Space

- LVDS driver, receiver, repeater, transceiver
- Space Ethernet PHY transceiver
- Rad-hard IP cores
- Signal conversion, signal processing

#### Non-space (under development)

- Hi-rel. Rad-tolerant
- Defence & Security, Nuclear, Aeronautics, Telecom...



### TECHNOLOGIES & TOOLS

Own proprietary **rad-hard IPs** and libraries in several technologies



Reliable design flow and EDA tools

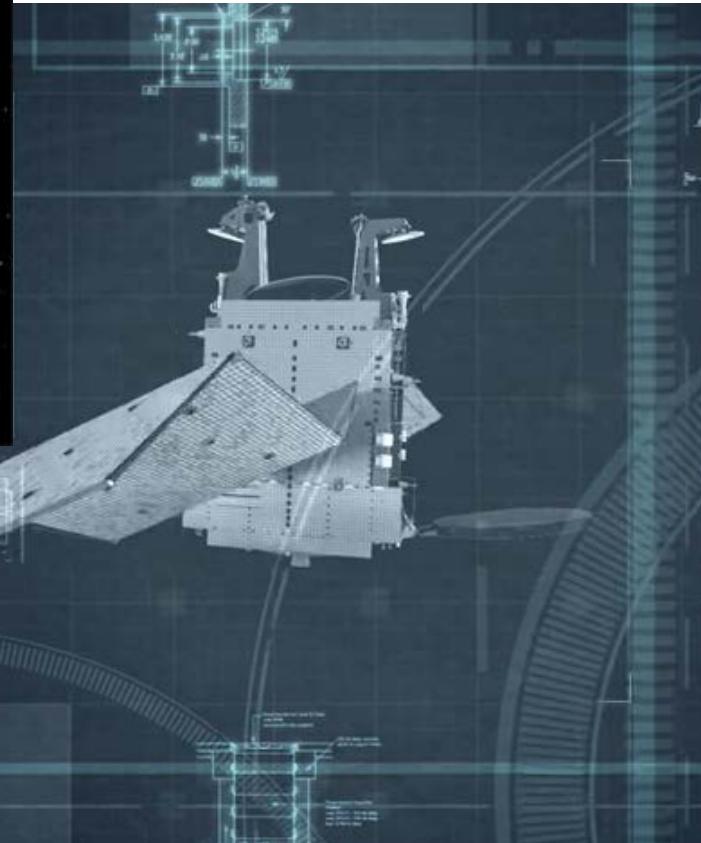


In-house radiation simulation tools, Electronic Labs, PCB design and test setup development



# ABOUT ARQUIMEA

## Microelectronics – Flight Heritage

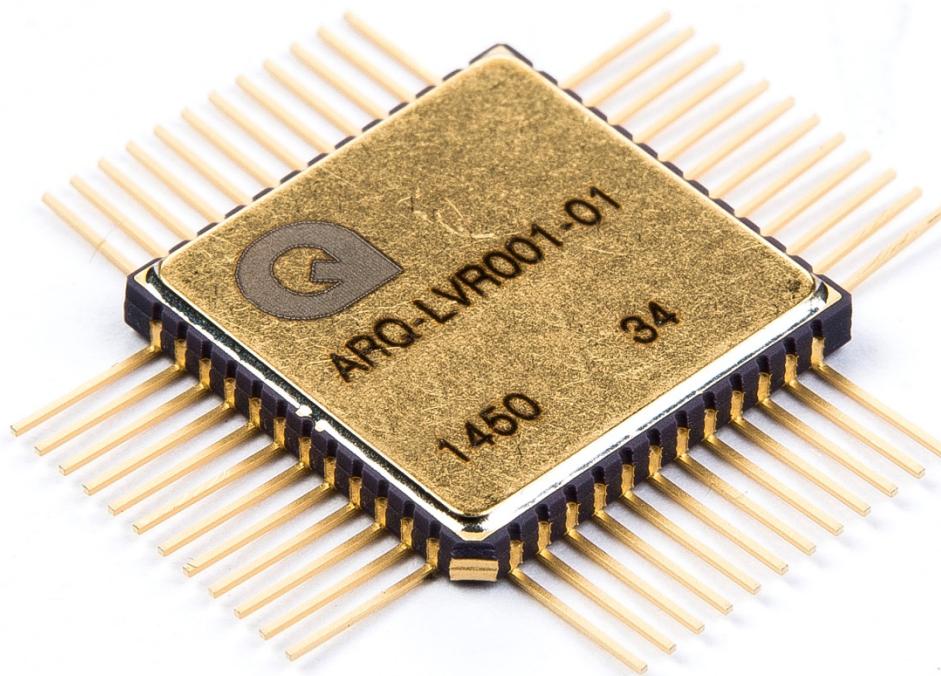


Supplier of Hispasat 36W-1 GEO communications satellite.

**624 spaceflight chips in a single mission**

[Mission video](#)

# RAD-HARD 500Mbps LVDS OCTAL REPEATER

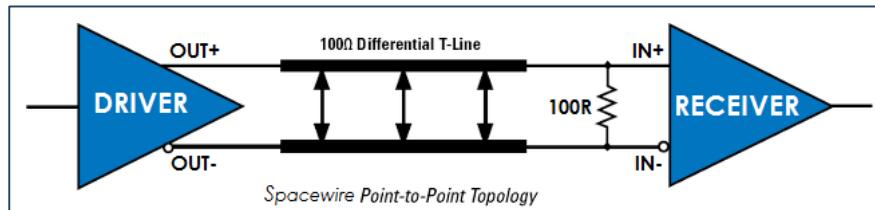


# LVDS REPEATER

## Introduction

### CONTEXT

- **SpaceWire increased demand** for European space programs
- **Existing rad-hard devices** coming from the US market – ITAR
- **Existing Commercial devices** without **key features** like fail-safe, cold sparing or extended common mode



### ECI (European Components Initiative)

- **ITAR Free – LVDS European alternative**
- **Compatible with existing products**
- **Availability, Cost and Schedule**
- **Suitability for Space** (technical, radiation and reliability features)

### LVDS PRODUCT FAMILY

- **ARQUIMEA** self-funded activity
- Development of a **European rad-hard LVDS family** based on **ESA Project outcomes**

# LVDS REPEATER

## Objectives and Requirements

### REFERENCES

- ESTEC/ITT AO/1-6922/11/NL/LvH
- ESA Contract ESTEC-4000105886

### PROJECT OBJECTIVES

- **LVDS European alternative** without ITAR restriction
- **LVDS Octal Repeater IC** development and qualification
- **LVDS Driver & LVDS Receiver IP cores**
- **Added Features** (cold spare, fail-safe, extended common mode)
- **Application to EPPL Parts List**

# LVDS REPEATER

## Objectives and Requirements

### GENERAL REQUIREMENTS

- **500Mbps operation** requirement
- **LVDS standard TIA/EIA-644** Full Compliance
- **Compatible** with US Devices
- **IHP SGB25V Library** (Hot Carrier Injection, ESD protections & Cold-spare)
- **5V tolerant TTL Digital Input**

### ADDITIONAL FEATURES

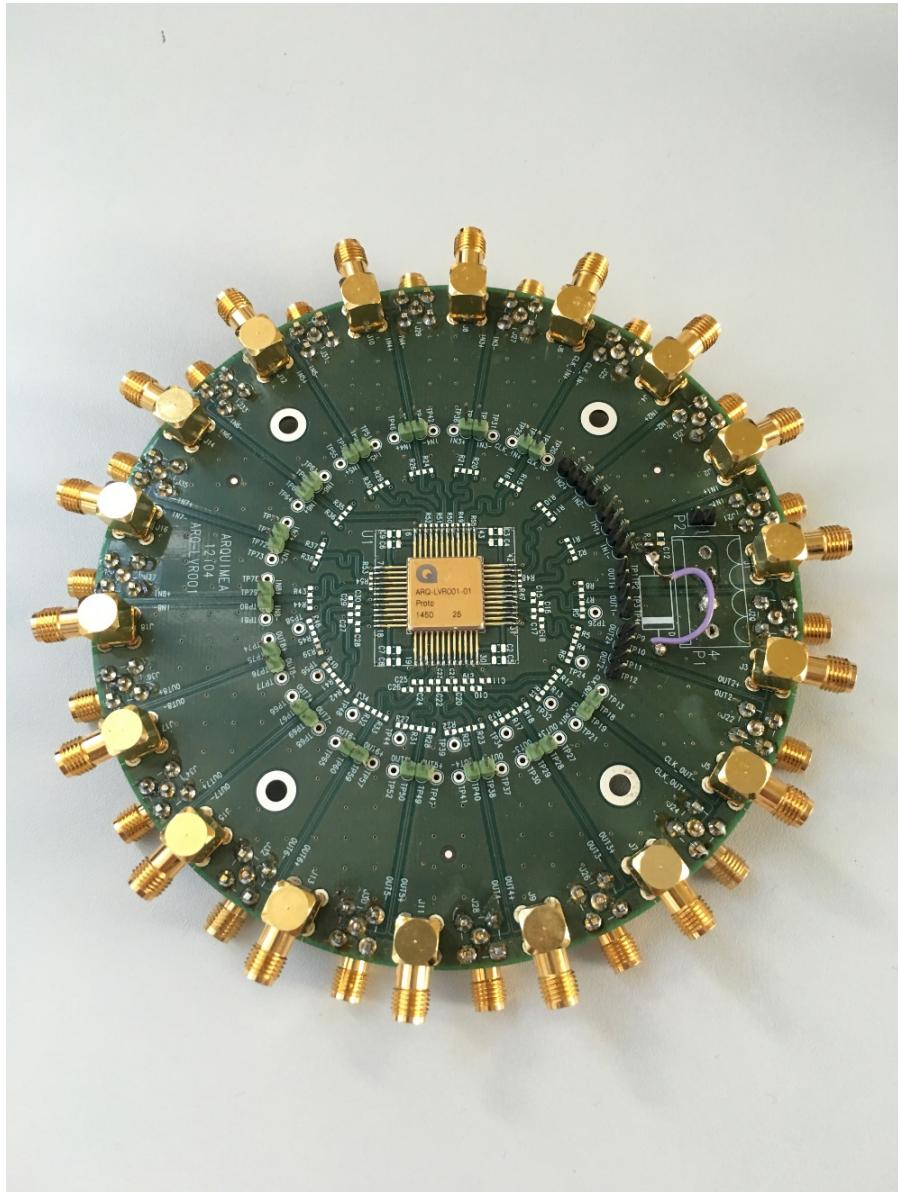
- **Extended Input Common Mode** [-4V to +5V] (Attenuator network required)
- **Input Hysteresis** (25mV)
- **Fail-safe Protection** (Patent compliance, Input Threshold Levels)

# LVDS REPEATER

## Objectives and Requirements

### TEST SET-UP challenges

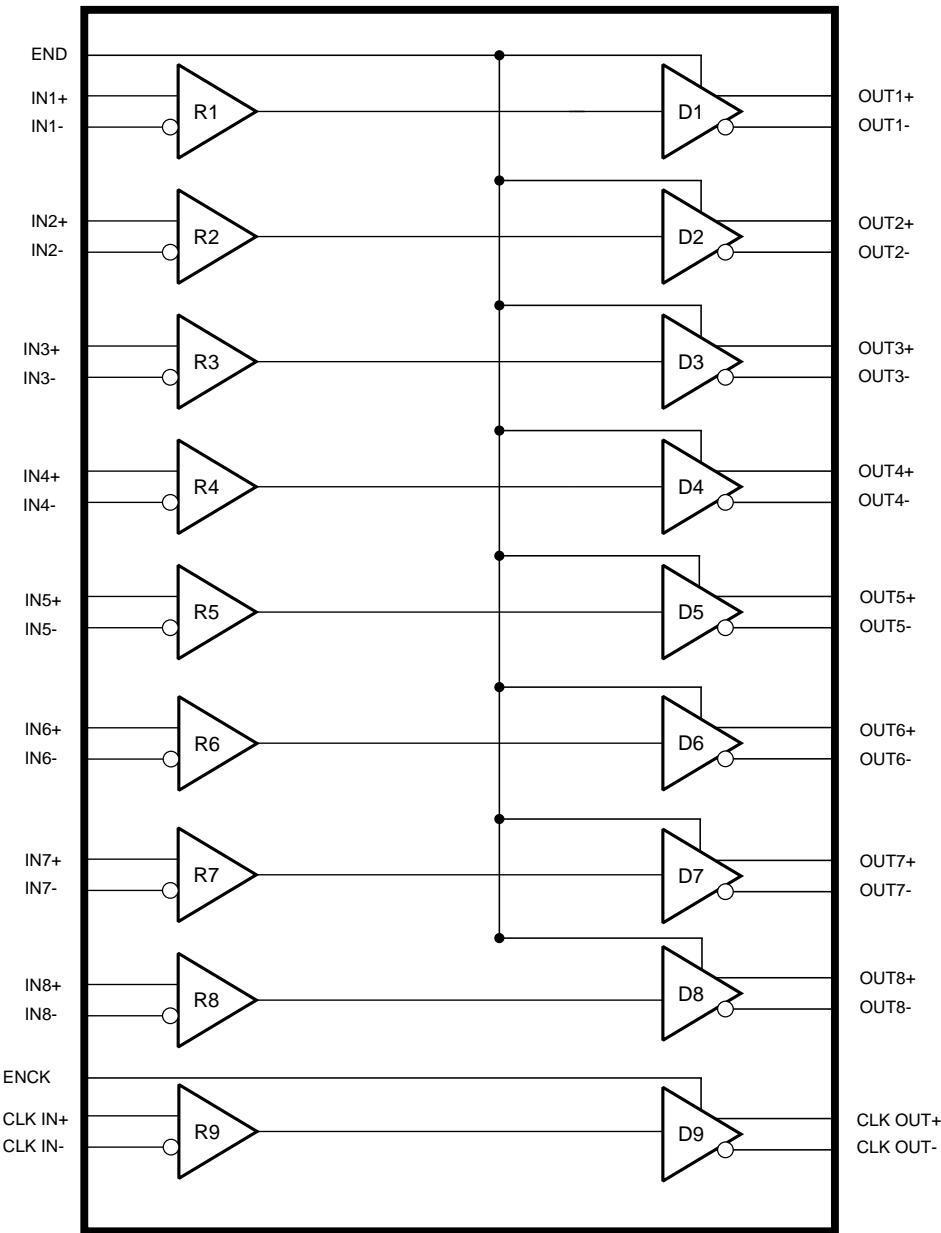
- Jitter
- Propagation time
- Skew Parameters
- Leakage Currents



# LVDS REPEATER

## Features

## BLOCK DIAGRAM

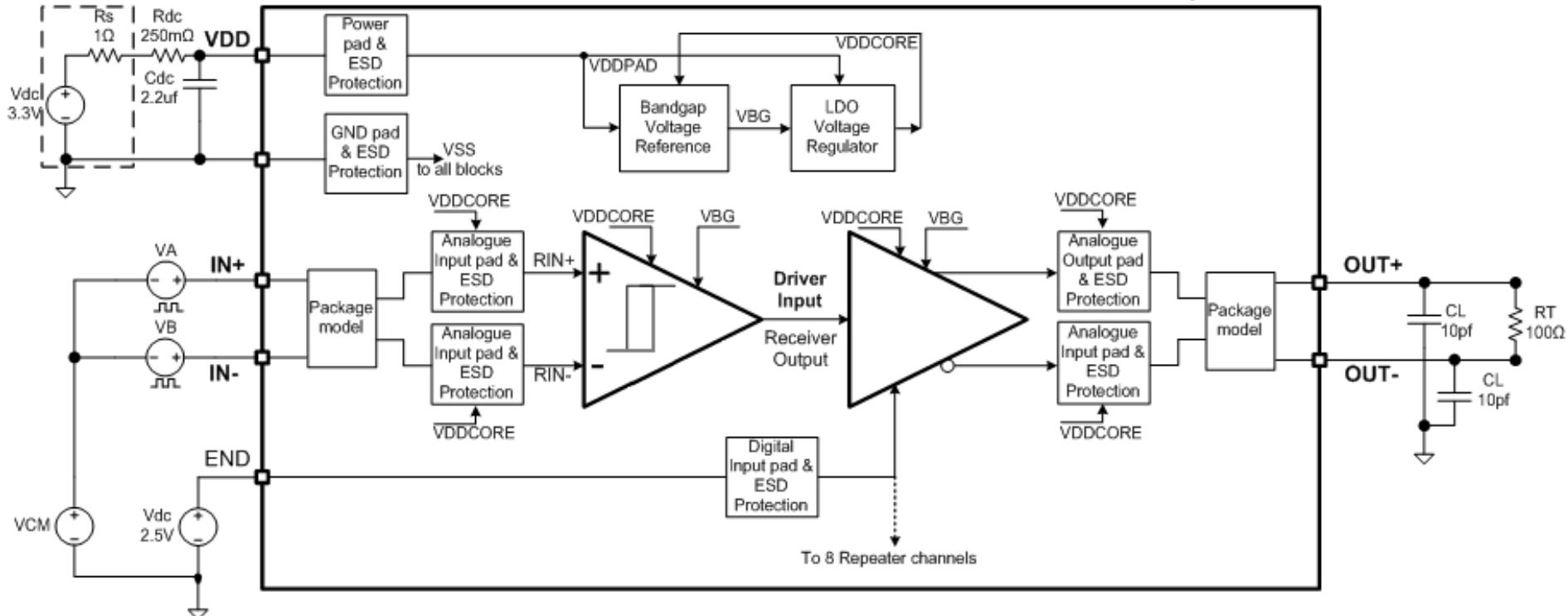


# LVDS REPEATER

## Features

## TOP LEVEL SCHEMATIC

Octal LVDS Repeater TOP



# LVDS REPEATER

## Features

## PROJECT PARTNERS

DEVELOPMENT FLOW	SUPPLY CHAIN	
DEFINITION & FEASIBILITY ANALYSIS	ARQUIMEA	
DESIGN – OVERALL	ARQUIMEA	
DESIGN – ESD PROTECTIONS	SOFICS	
DESIGN VERIFICATION	ARQUIMEA	
MANUFACTURING (SGB25V MPW)	IHP	
ASSEMBLY	SERMA (HCM)	
VALIDATION	ALTER	

# LVDS REPEATER

## Features

### FOUNDRY PROCESS

- IHP Microelectronics (Germany)
- SGB25V – 250nm SiGe BiCMOS Technology
- Qualified process based on JEDEC Standard JP001.01
- Rad-hard (TID, SEL free)



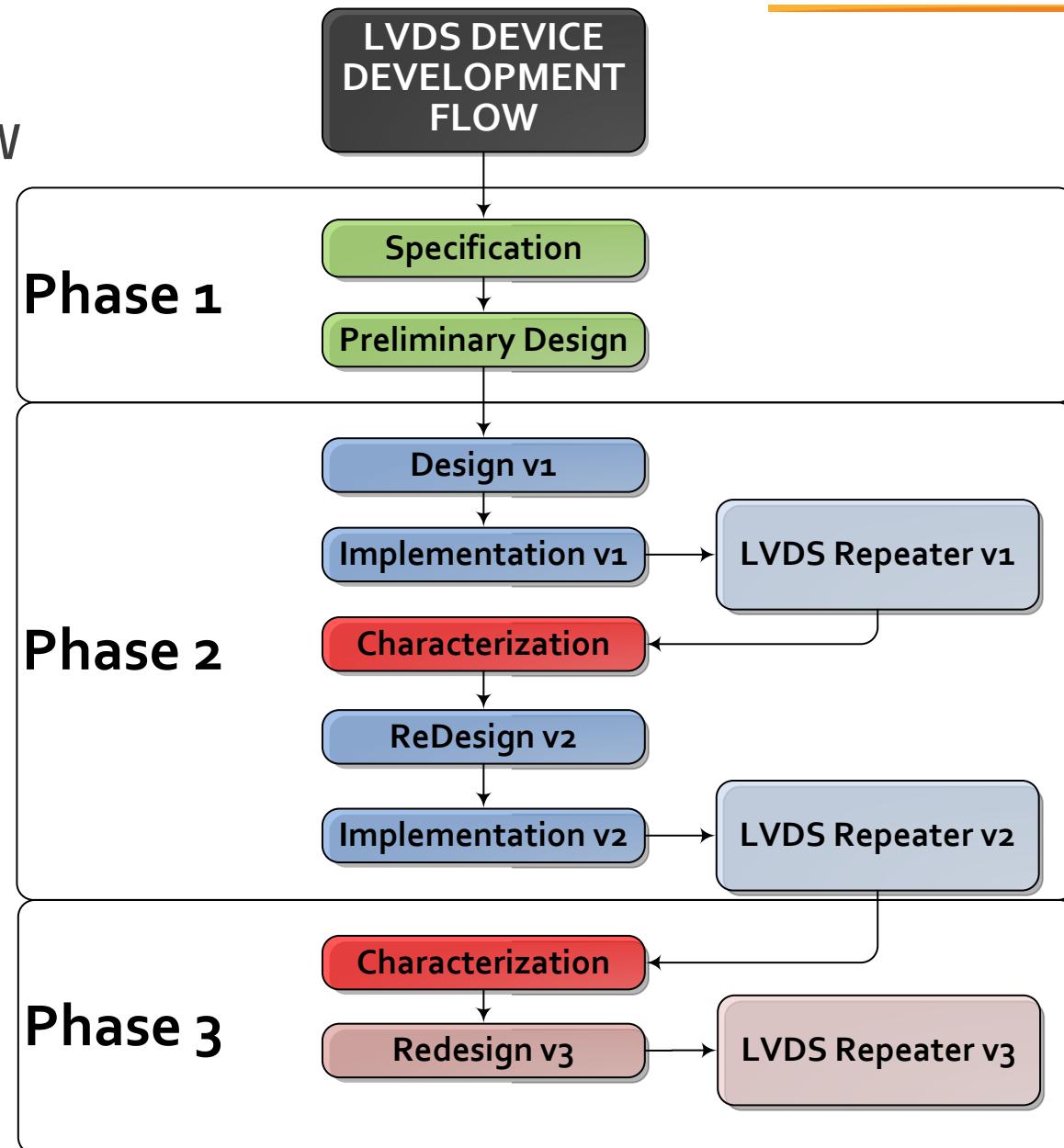
### TECHNOLOGY CHALLENGES

- Hot Carrier Injection Issue at 3.3V → Use of Level Shifters for Digital Pads
- ESD protections and cold-spare for IO pads

# LVDS REPEATER

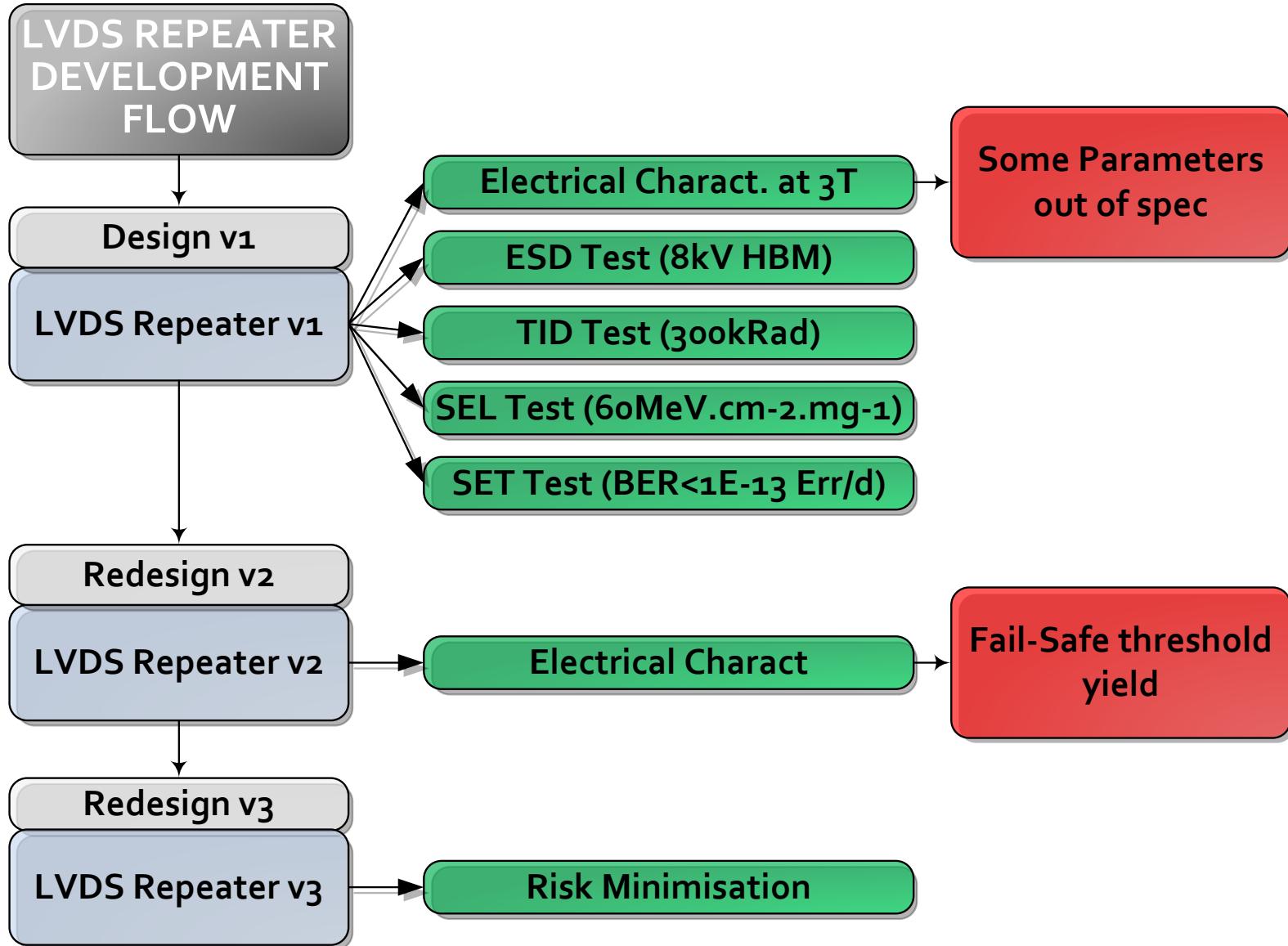
## Implementation

### DEVELOPMENT FLOW



# LVDS REPEATER

## Implementation



# LVDS REPEATER

## Implementation

### REDESIGN

- ESD protection improvement to lower **cold-spare leakage** current
- Passive circuits slight modifications to improve Jitter, **Iccz** and **IoZ**
- Active circuit update with known topologies to improve:
  - Differential Output Voltage (**Vod**) at low temperature
  - Vt** Input threshold including Hysteresis
  - Fail-safe Voltage Threshold** (Extensive simulation to insure the yield)

### RISK MINIMISATION

- Extensive simulation in corners, Montecarlo
- Very Low Parametric Risk
- Very Low TID Risk
- Very Low ESD risk
- Very Low SEE risk
- Metal Fix possibility



# LVDS REPEATER

## Results

### GENERAL PERFORMANCES

**Low Power Consumption** (<100mA)

**High speed Operation** (tested up to 800Mbps)

**8kV HBM ESD protection and rad-hard design**

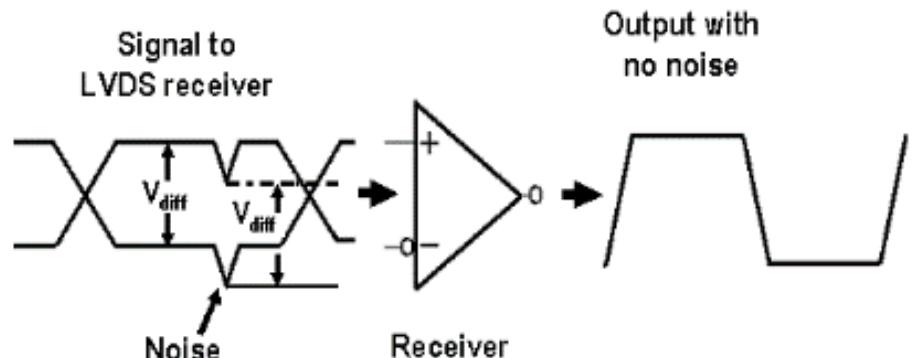
### RECEIVER PERFORMANCES

**25mV input Hysteresis** (impact in Noise performance)

**Cold Spare protection** (avoid failure propagation in case of shut-off power supply)

**Fail-Safe protection** (avoid failure propagation in case of SC or OC on differential Input lines)

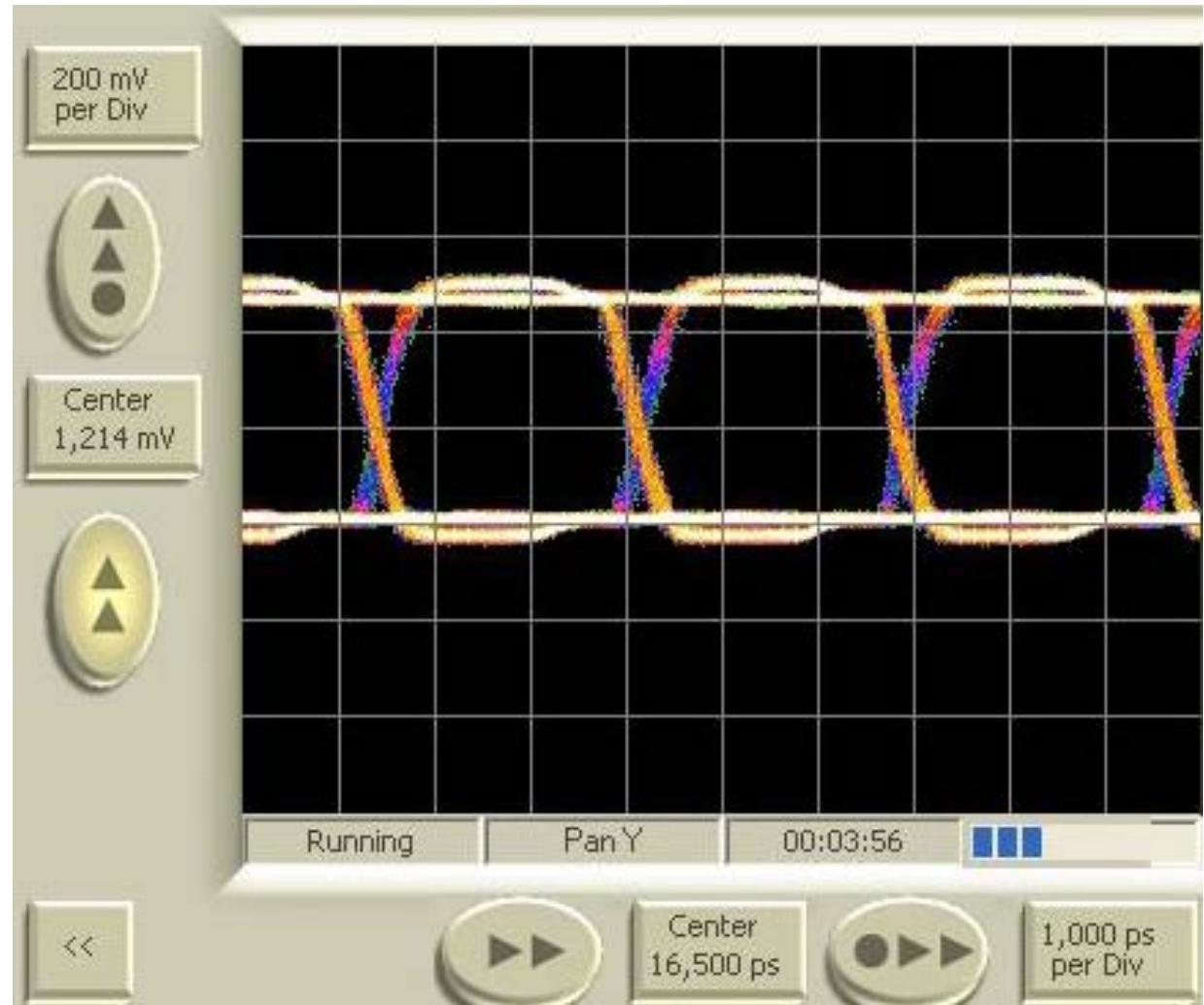
**Extended Common Mode Range** (-4V to 5V; Good behavior against **EM and Ground bouncing**)



# LVDS REPEATER

## Results

### EYE DIAGRAM (400Mbps)



# LVDS REPEATER

## Flight Opportunities

### PLATO (ESA program)

**Under Analysis** for potential use in the program

**Cold Spare buffer** for other non-cold-spare LVDS devices

**Low Power consumption** contrary to LVDM devices



PLAnetary Transits and Oscillations of stars (PLATO) is the third medium-class mission in ESA's Cosmic Vision programme. Its objective is to find and study a large number of extrasolar planetary systems, with emphasis on the properties of terrestrial planets in the habitable zone around solar-like stars.

# LVDS REPEATER

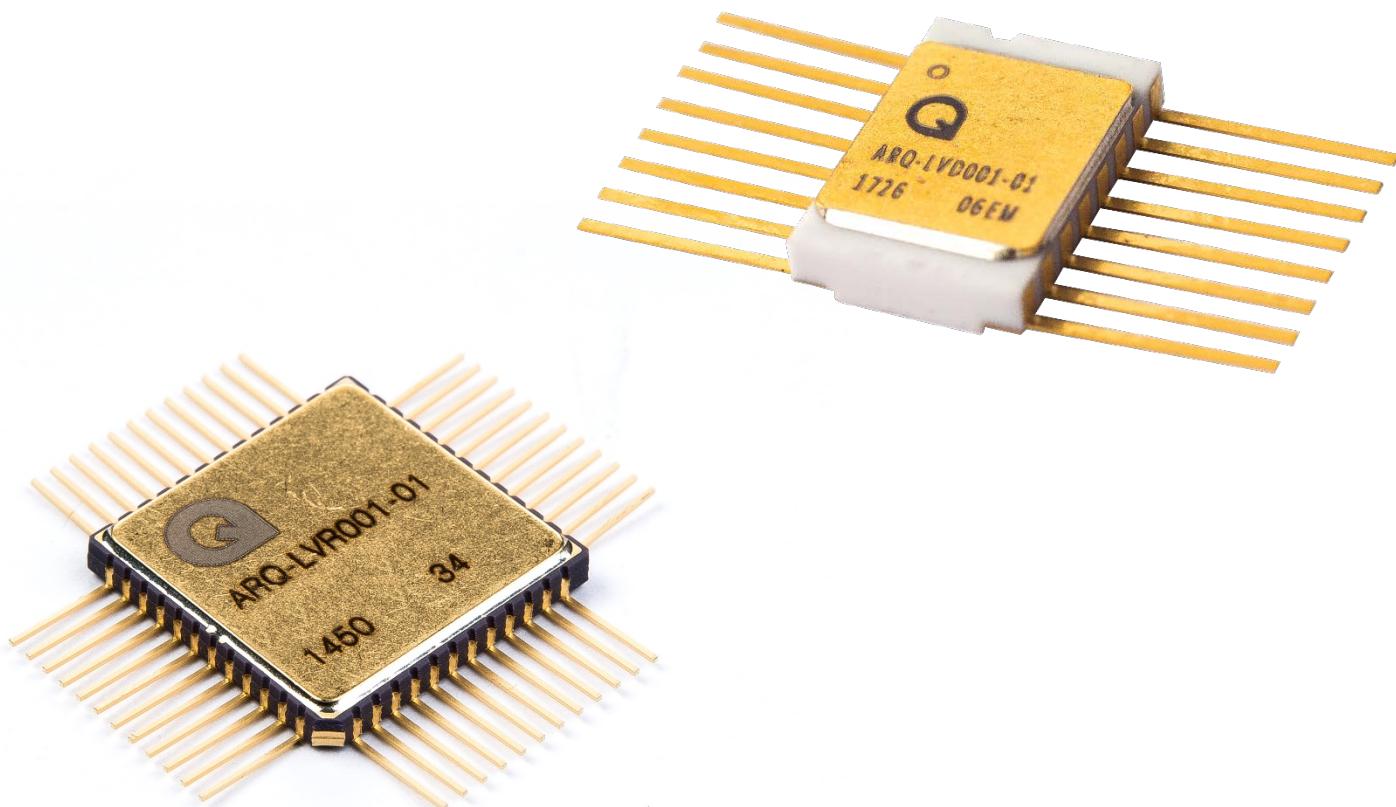
## EPPL Application

### EPPL Requirements

- Potential use in flight hardware (SpW)
- Potential use for current or future program (e.g. PLATO)
- Space-Level Supply chain
- No Export Restriction for ESCC user industries
- No Notice of obsolescence
- Radiation performance
- Available US or European equivalents (e.g. ST, COBHAM/AEROFLEX)

- No Quality or Reliability problems (High confidence)
- Procurement Specification (Pending Qualification)
- ESCC Qualified or Evaluated Components (LVDS Family)

# LVDS FAMILY



# LVDS FAMILY

## General

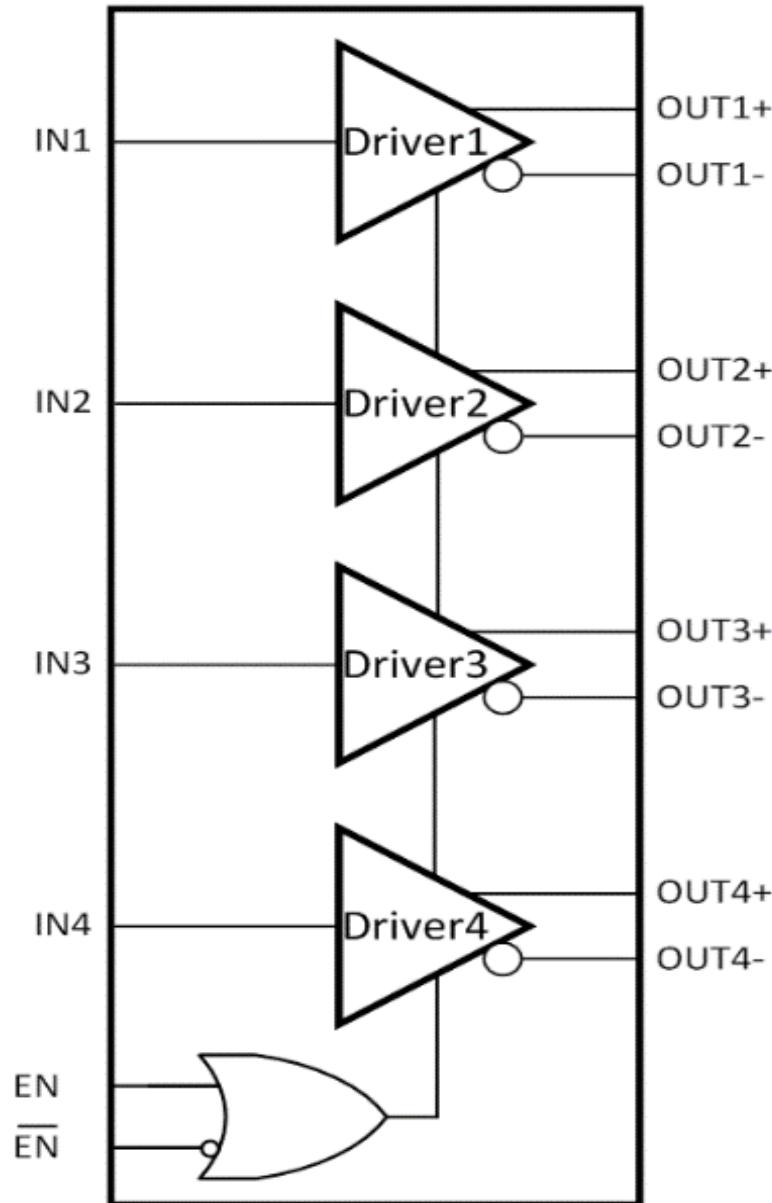
- **Development and qualification of European LVDS product family:**  
Driver, Receiver, Transceiver, Repeater
- ARQUIMEA's self-funded product development  
Using **synergies from ESA LVDS Repeater project**
- **Pin-to-pin compatible** with existing US products
- **Same package type** and **dimensions in all devices**  
(except Repeater CQFP-48 vs FP-48)
- **Fully European supply chain, ITAR-free**

# LVDS FAMILY

## General – Design

### BLOCK DIAGRAM

Quad Driver ARQ-LVD001

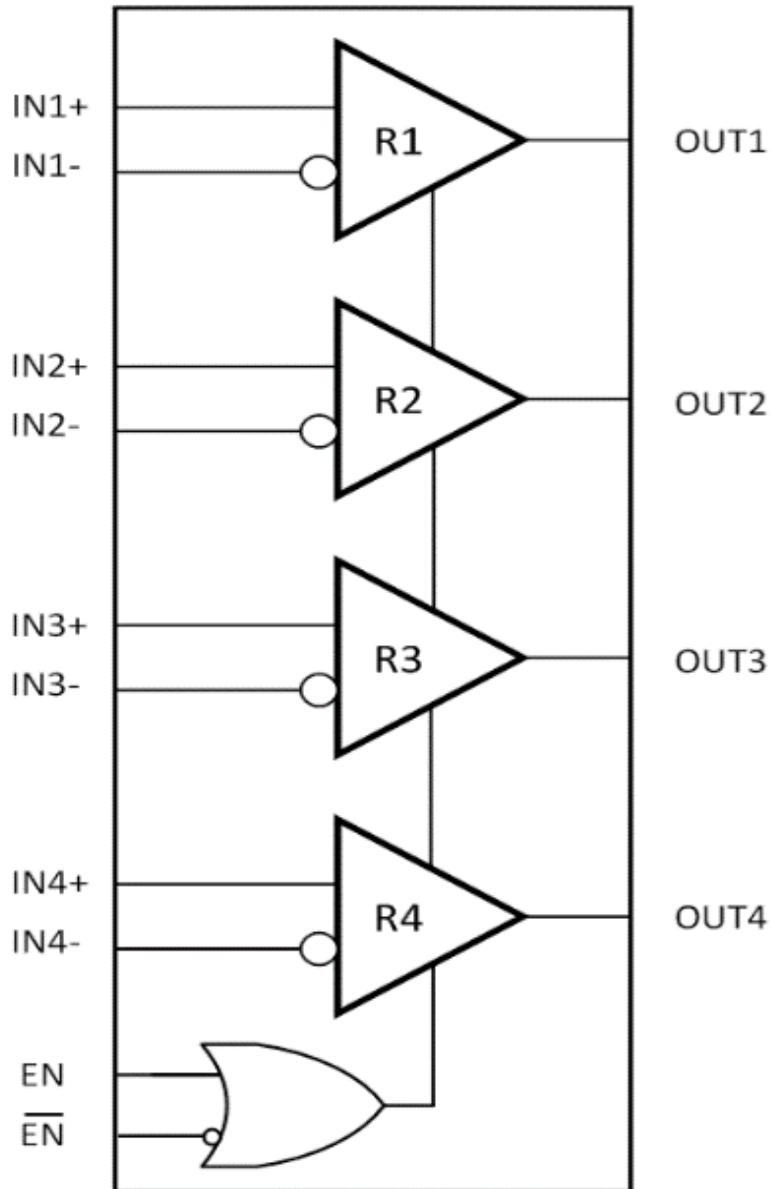


# LVDS FAMILY

## General – Design

### BLOCK DIAGRAM

Quad Receiver ARQ-LVR002

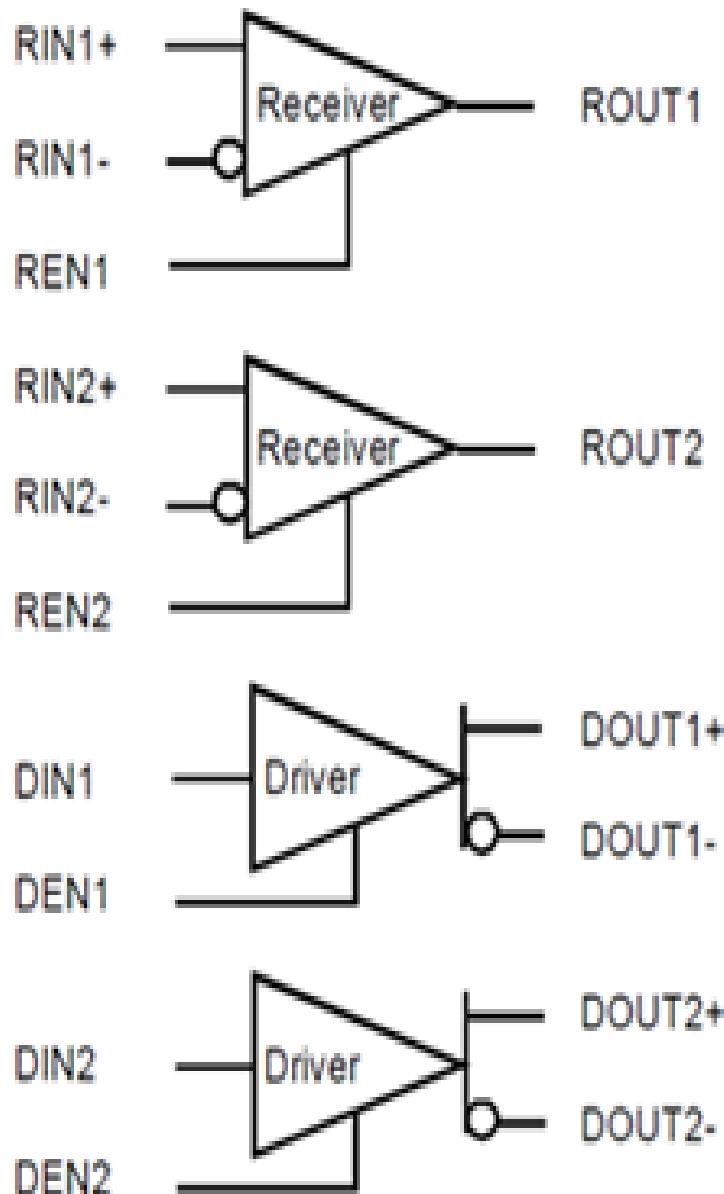


# LVDS FAMILY

## General – Design

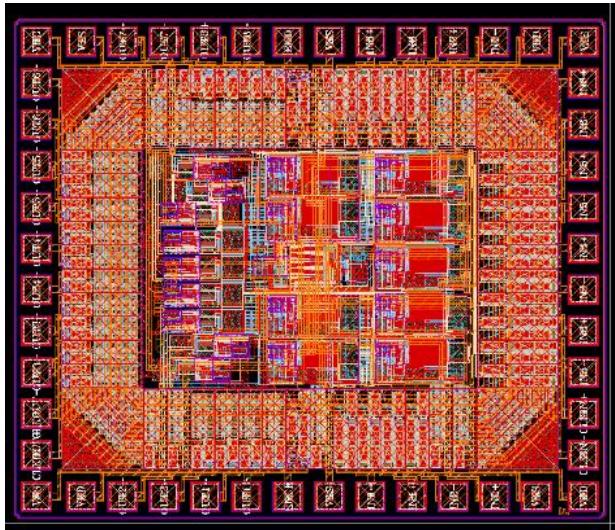
### BLOCK DIAGRAM

Quad Transceiver ARQ-LVT001

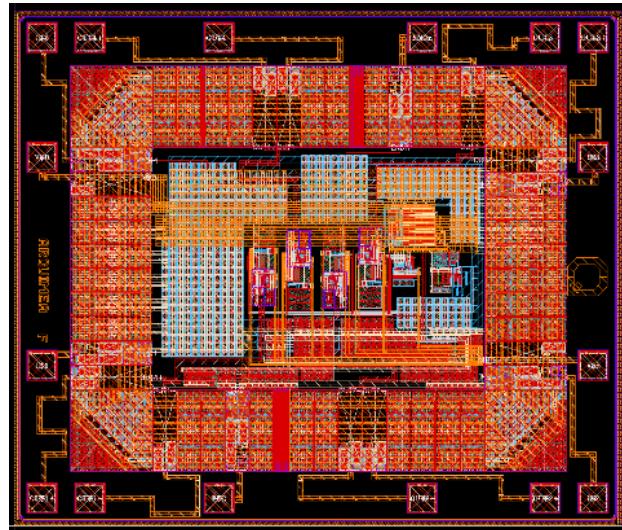


# LVDS FAMILY

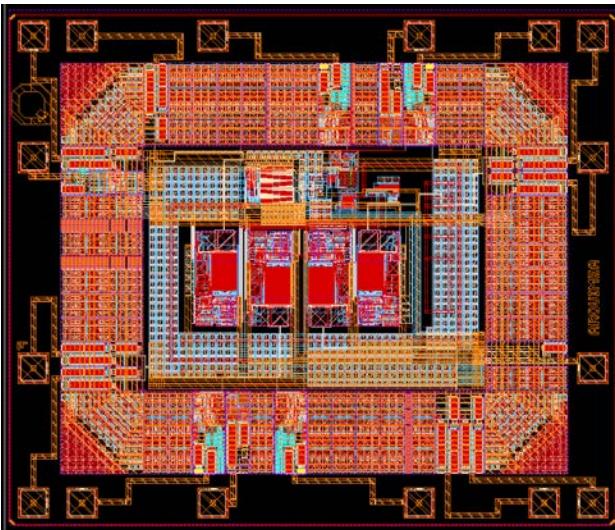
## General – Layout



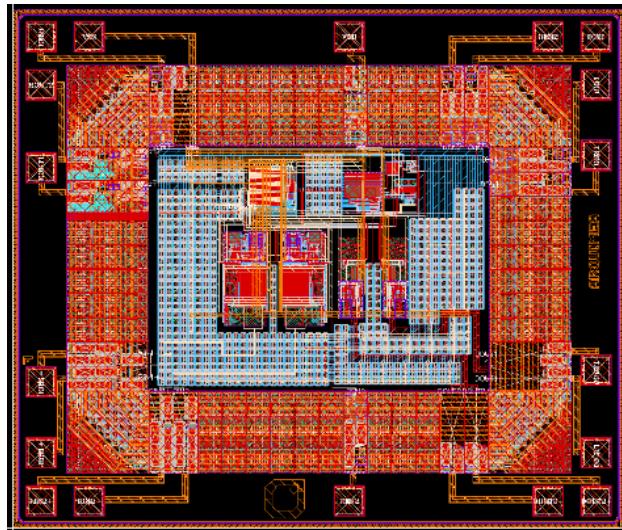
Octal Repeater ARQ-LVP001



Quad Driver ARQ-LVD001



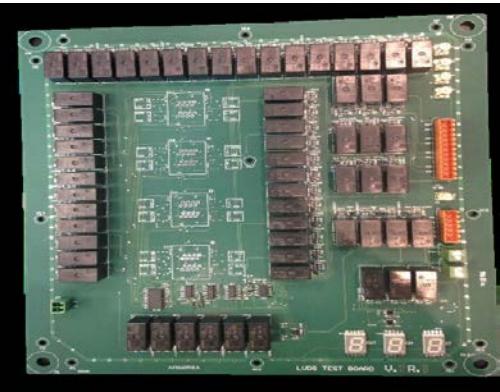
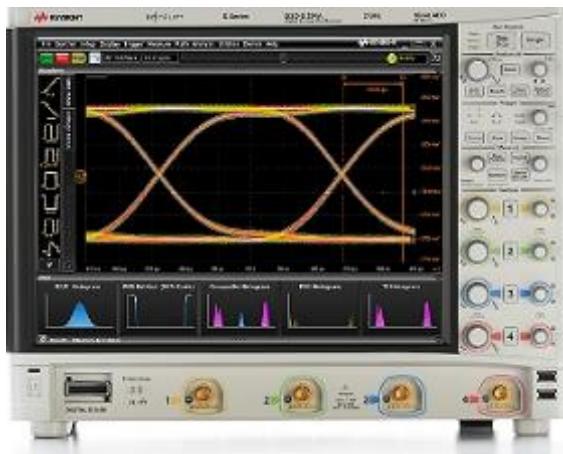
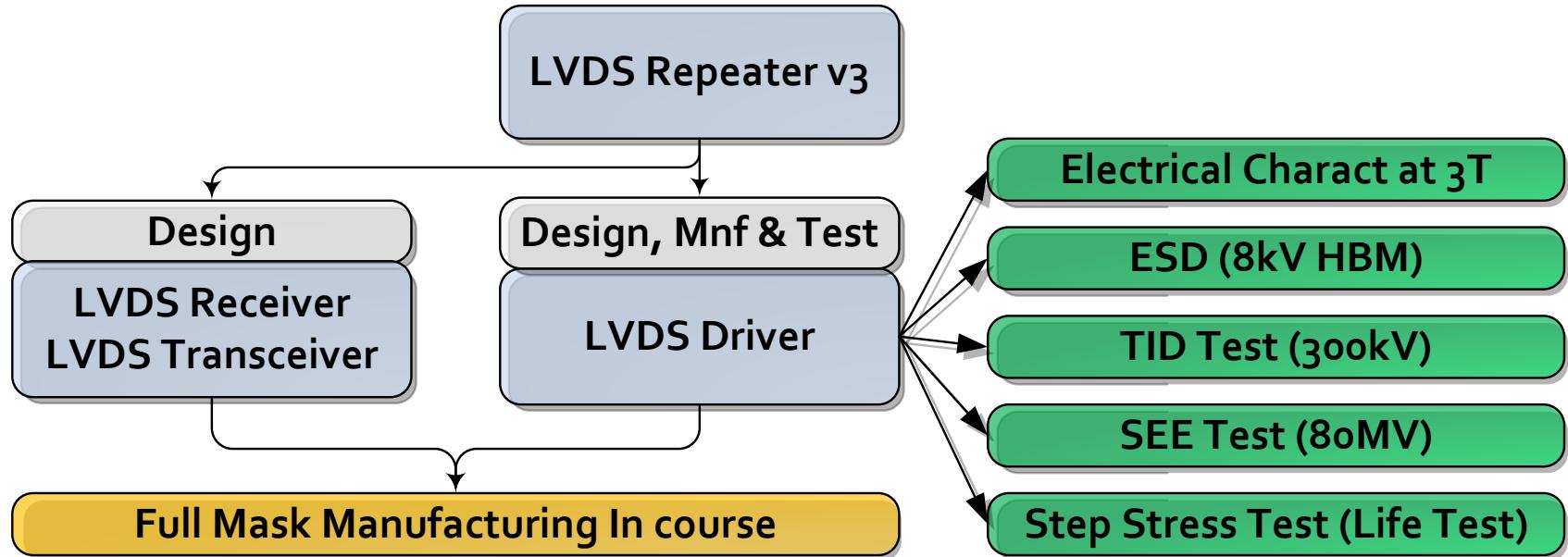
Quad Receiver ARQ-LVR002



Dual Transceiver ARQ-LVT001

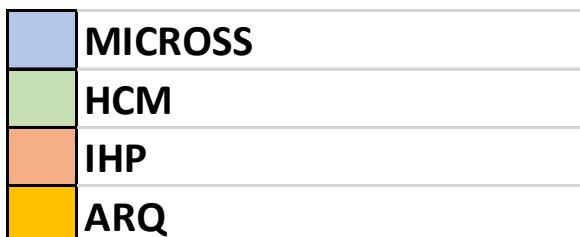
# LVDS FAMILY

## Development Status



# LVDS FAMILY

## Development Status

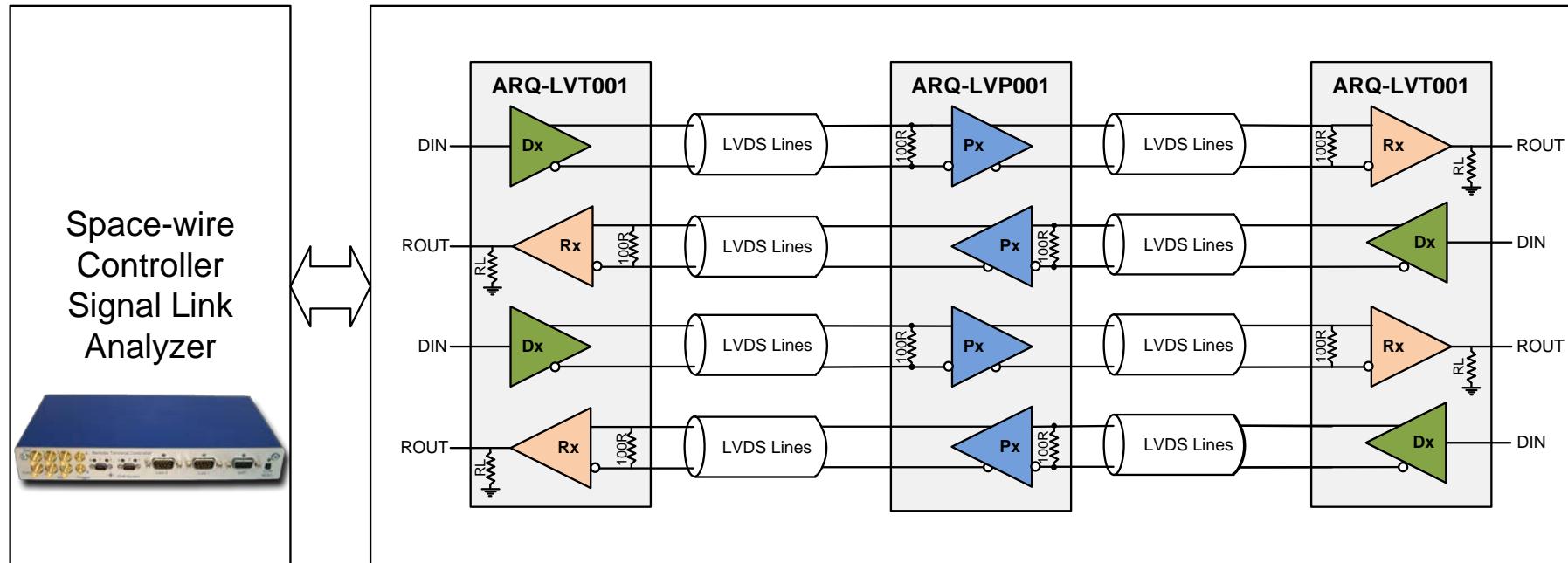


# LVDS FAMILY

## Development Status

### DEMONSTRATION KIT based on [ECSS-E-ST-50-12](#) (SpW standard)

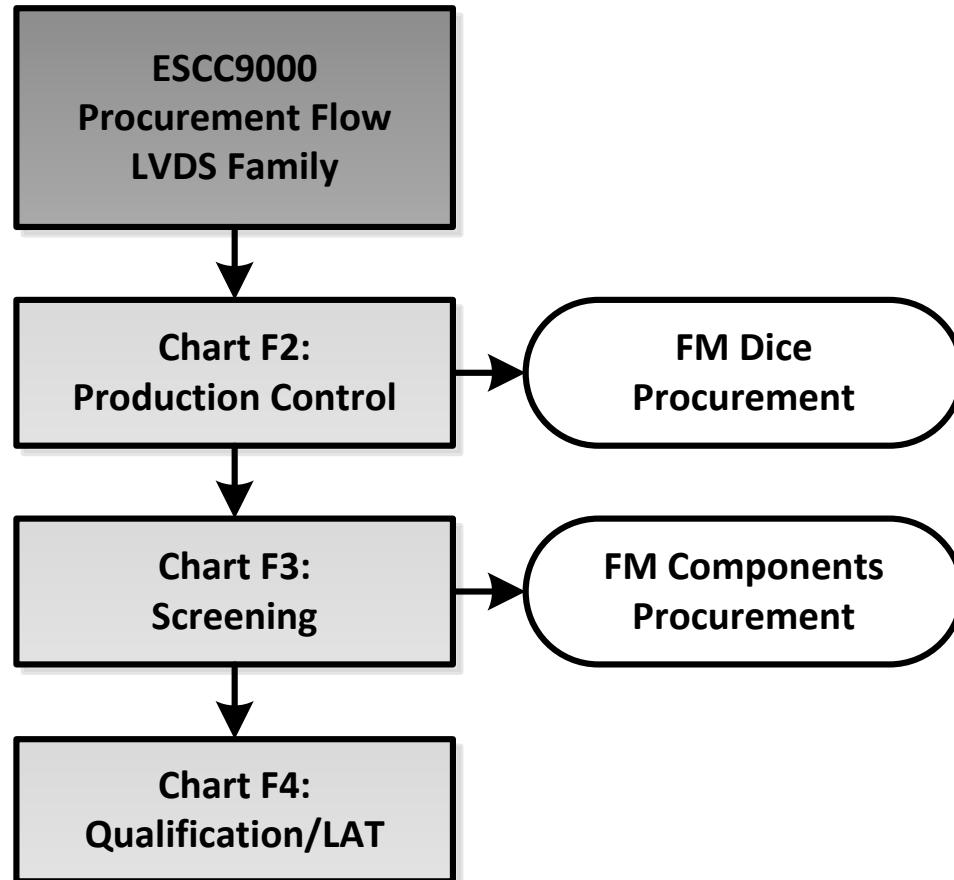
- LVDS devices **emulation**
- **Cabling (type, length)** and **connectors** effects on performances  
Verification of **PHY layer & Data Transfer protocol**
- **Compatibility verification** with other LVDS devices



# LVDS FAMILY

## Procurement Flow

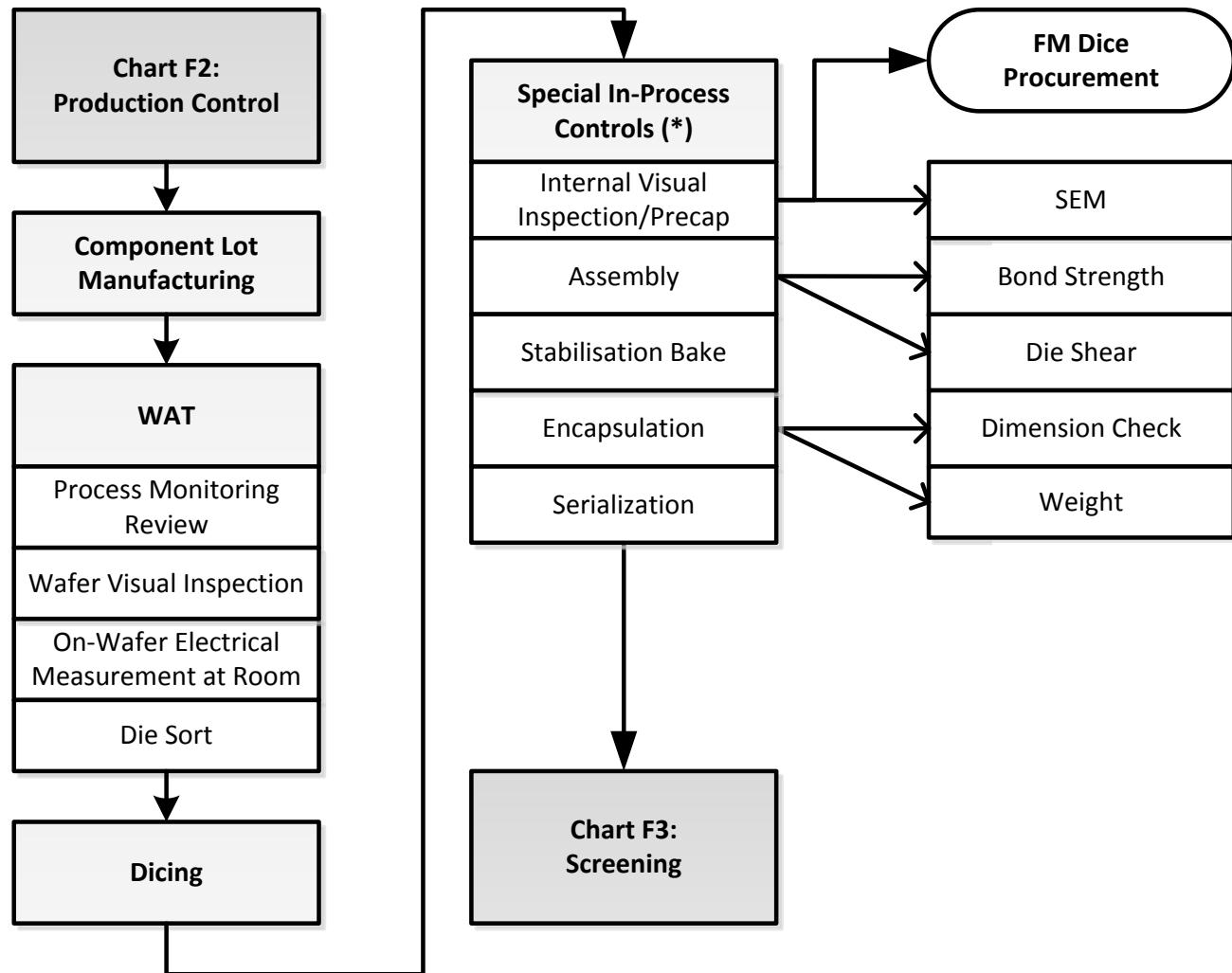
### GENERAL



# LVDS FAMILY

## Procurement Flow

# PRODUCTION CONTROL



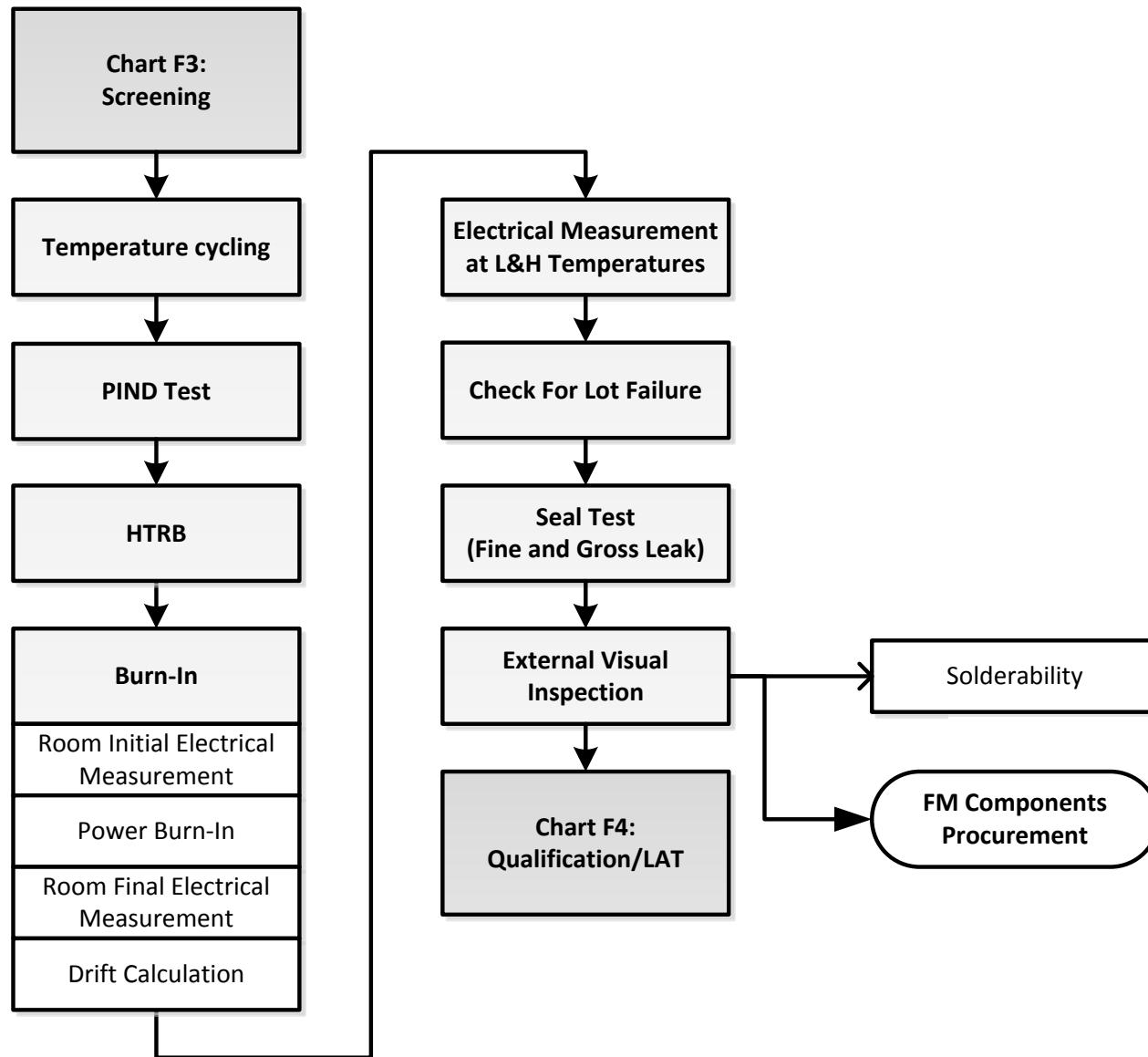
### Notes:

(\*) Precap Inspection can be proposed to third party

# LVDS FAMILY

## Procurement Flow

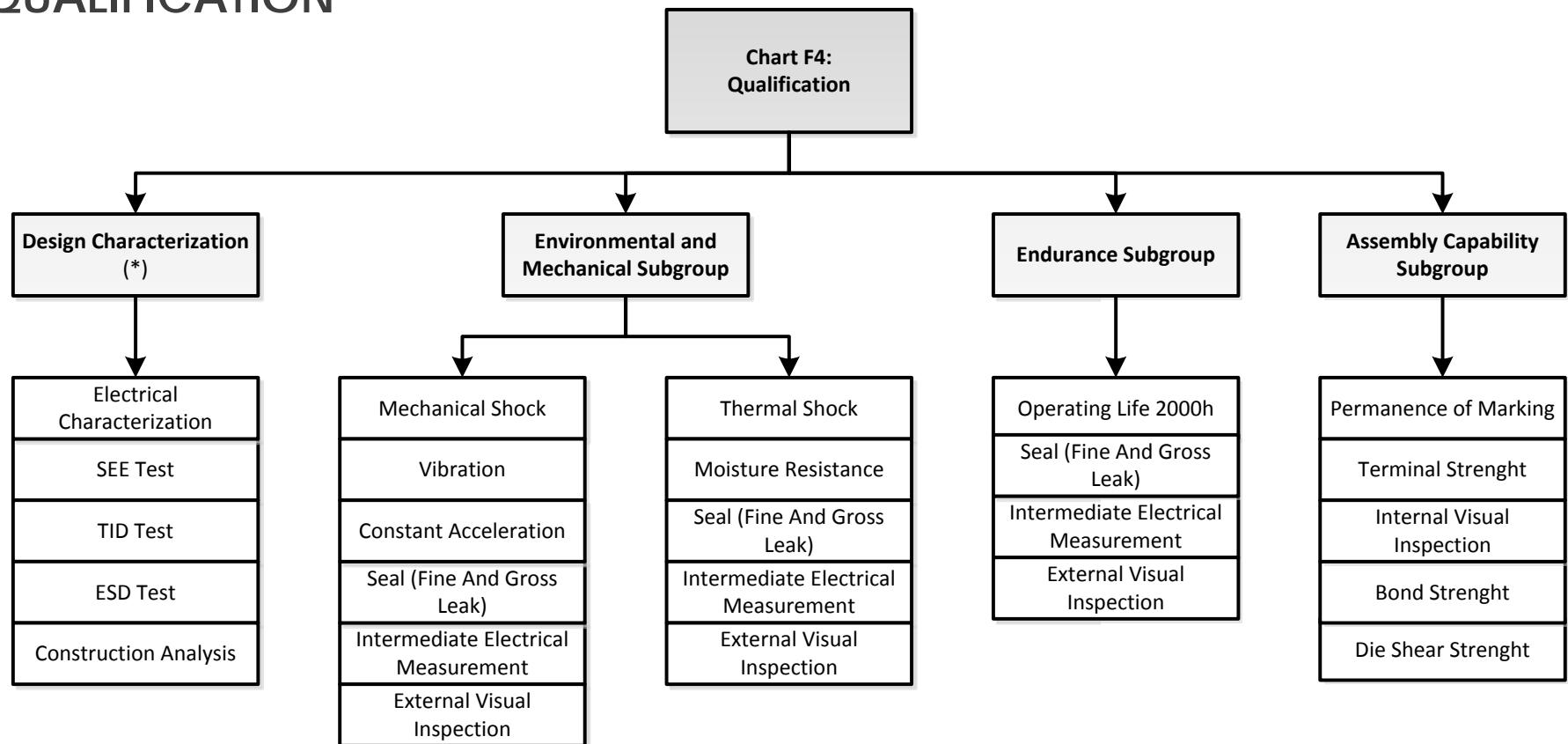
### SCREENING



# LVDS FAMILY

## Procurement Flow

### QUALIFICATION



\* If no representative data available

# LVDS FAMILY

## Results & Conclusions

- ✓ LVDS Octal Repeater – ESA project **successfully completed**
- ✓ Additionally, an **entire LVDS family** was developed

Driver, Receiver, Transceiver and Repeater

- ✓ **Compatible** with US devices. **Key parameters improved**
- ✓ **Fully European** supply chain. ITAR free
- ✓ First **space-qualified chips** using IHP processes
- ✓ Development and **qualification ongoing**

Samples and evaluation boards already available (Driver and Repeater)

QMs available in Q3-18

FMIs available in Q4-18

# LVDS FAMILY

## Results & Conclusions

### Preliminary Datasheets available

**ARQUIMEA** ARQ-LVP001  
RAD-HARD Octal 500 Mbps Bus LVDS Repeater

**FEATURES**

- 500 Mbps low jitter fully differential data path
- 250 MHz clock channel
- 3.3 V power supply
- LVCMOS/LVTTL compatible inputs
- Low power consumption
- 6mA output driver short circuit (OUT+, OUT-)
- Clock splicing on all pins
- 1.5ns Propagation delay in temperature range
- Extended LVDS Input Common Mode (-4...+5)V
- Receiver input threshold  $\pm 100$  mV
- 25mV (typ.) Input hysteresis
- Radiation tolerant: 300 krad(S)
- Latch-up free up to 67 MeVcm<sup>2</sup>/mg
- ESD tolerance: 1000 V (HBM)
- Packaging: 48-pin Ceramic Quad Flat Pack (CQFP)
- ANSI/TIA/EIA 644a LVDS Standard Compliant
- Space level

In addition, the Octal LVDS Repeater supports an overall TRI-STATE function that may be used to disable the output stages, disabling the load current, and thus dropping the device to an ultra-low idle power state.

All pins, including CMOS Input, have Cold Spare capabilities. The pins will be high impedance when VDD is tied to VSS.

The intended buffers of LVDS receiver include an active internal fail-safe circuit that sets the output of the receiver to a known high state when the following conditions occur: one or the two inputs floating or inputs shorted.

The extended common mode range allows high voltage drops between ground planes without affecting performance.

**APPLICATIONS**

ARQUIMEA's ARQ-LVP001 provides the basic bus repeater function. The device operates as a 9 channel LVDS repeater, allowing for bidirectional data transmission, restoring the LVDS amplitude, allowing to drive another media segment, enabling isolation of segments or long-distance applications.

The intended application of these devices and signaling technique is for both spacewire point-to-point baseband (single termination) and multipoint transmitters for point-to-point or multi-drop interconnects. It is specifically designed for the bridging of multiple backplanes in a system while consuming minimal power with reduced EMI.

The transmission media may be printed-circuit board traces, backplanes, or cables.

**RADIATION HARDENING**

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
TID	300	-	-	krad	Only validated on
SEL	-	-	-	MeVcm <sup>2</sup> /mg	original design
SEE performance	1E-13	-	-	Err/Bit/day	for a GEO orbit
TBC	-	-	-		ARQ-LVR001

More information about radiation hardening features and radiation test conditions is available under request.

**AVAILABLE OPTIONS**

PRODUCT	QUALITY LEVEL	PACKAGE (*)	OPERATING TEMPERATURE	ORDERING NUMBER	VARIANT DETAIL	TRANSPORT MEDIA
ARQ-LVP001	Standard	48 pin CQFP	-55°C to 125°C	ARQ-LVP001-02	Without Fail-Safe	50-pieces tray
ARQ-LVP001	Standard	48 pin CQFP	-55°C to 125°C	ARQ-LVP001-03		50-pieces tray

ARQ\_12104\_DSH\_004\_issue\_02, Date: 20-09-2017

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**ARQUIMEA** ARQ-LVD001  
RAD-HARD Quad 500 Mbps Bus LVDS Driver

**FEATURES**

- 500.0 Mbps low jitter data path
- 3.3 V power supply
- LVCMOS/LVTTL compatible inputs
- Low Power Consumption
- 6mA output driver short circuit (OUT+, OUT-)
- Clock splicing on all pins
- 2ns Propagation delay in temperature range
- Radiation tolerant: 300 krad(S)
- Latch-up free up to 67 MeVcm<sup>2</sup>/mg
- ESD tolerance: 1000 V (HBM)
- Packaging: 16-pin Ceramic Flat Pack (FP-16)
- ANSI/TIA/EIA 644a LVDS standard Compliant
- Space level

All pins, including CMOS Input, have Cold Spare capabilities. The pins will be high impedance when VDD is tied to VSS.

The intended buffers of LVDS receiver include the bridging of multiple bus consuming minimal power.

In addition, the Quad LVDS overall TRI-STATE function disable the output stages, and thus dropping the device power state.

All pins, including CMOS Input, have Cold Spare capabilities. The pins will be high impedance when VDD is tied to VSS.

The intended application of these devices and signaling technique is for point baseband (single termination) and multipoint transmitters for point-to-point or multi-drop interconnects. The device is specially designed for the bridging of multiple backplanes in a system while consuming minimal power with reduced EMI.

The transmission media may be printed-circuit board traces, backplanes, or cables.

**APPLICATIONS**

The ARQ-LVD001 provides functions which allow isolate distance applications.

The intended application of these devices and signaling technique is for point baseband (single ter (double) termination) data controlled impedance media. The transmission media may be printed-circuit board traces, backplanes, or cables.

**DESCRIPTION**

ARQUIMEA's ARQ-LVD001 device is a Quad Bus Low Voltage Differential Signals (LVDS) Driver intended for low-power consumption and space operation. Data path consists in a fully differential LVDS output with its associated fully differential LVDS input with low noise generation and low width distortion.

The ARQ-LVD001 enables high speed LVDS data transmission for point-to-point or multi-drop interconnects. This device is specially designed for the bridging of multiple backplanes in a system while consuming minimal power with reduced EMI.

The transmission media may be printed-circuit board traces, backplanes, or cables.

**RADIATION HARDENING**

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
TID	300	-	-	krad	Only validated on
SEL	-	-	-	MeVcm <sup>2</sup> /mg	original design
SEE performance	1E-13	-	-	Err/Bit/day	for a GEO orbit
TBC	-	-	-		ARQ-LVR001

More information about radiation hardening features and radiation test conditions is available under request.

**AVAILABLE OPTIONS**

PRODUCT	QUALITY LEVEL	PACKAGE	OPERATING TEMPERATURE RANGE	ORDERING NUMBER
ARQ-LVD001	Standard	16-FP	-55°C to 125°C	ARQ-LVD001-02
ARQ-LVD001	ESCC9000	16-FP	-55°C to 125°C	ARQ-LVD001-03

(\*) Other packaging options, including raw die format, are also available under request.

ARQ\_15601\_DSH\_00

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**ARQUIMEA** ARQ-LVR002  
RAD-HARD Quad 500 Mbps Bus LVDS Receiver

**FEATURES**

- 500.0 Mbps low jitter data path
- 3.3 V power supply
- CMOS/LVTL compatible inputs/Outputs
- Low Power Consumption
- 6mA output driver short circuit (OUT+, OUT-)
- Clock splicing on all pins
- 2ns Propagation delay in temperature range
- Extended LVDS Input Common Mode (-4...+5)V
- Receiver input threshold  $\pm 100$  mV
- 25mV (typ.) Input hysteresis
- Fail Safe protection circuit
- Radiation tolerant: 300 krad(S)
- Latch-up free up to 67 MeVcm<sup>2</sup>/mg
- ESD tolerance: 1000 V (HBM)
- Packaging: 16-pin Ceramic Flat Pack (FP-16)
- ANSI/TIA/EIA 644a LVDS standard Compliant
- Space level

disable the output stages, and thus dropping the device power state.

All pins, including CMOS Input, have Cold Spare buffers. The pins will be high impedance when VDD is tied to VSS.

The input buffers of LVDS receiver include an active internal fail-safe circuit that sets the output of the receiver to a known high state when the following conditions occur: one or the two inputs floating or inputs shorted.

The extended common mode range allows high voltage drops between ground planes without affecting performance.

**APPLICATIONS**

The ARQ-LVR002 provides functions which allow isolate distance applications.

The intended application of these devices and signaling technique is for point baseband (single ter (double) termination) data controlled impedance media. The transmission media may be printed-circuit board traces, backplanes, or cables.

**DESCRIPTION**

ARQUIMEA's ARQ-LVR002 device is a Quad Bus Low Voltage Differential Signals (LVDS) Receiver intended for low-power consumption and space operation. Data path consists in a fully differential LVDS input with its associated LVCMOS/LVTTL output.

The ARQ-LVR002 allows high-speed LVDS data transmission for point-to-point or multi-drop interconnects. The device is specifically designed for the bridging of multiple backplanes in a system.

In addition, the Quad LVDS receiver supports an overall TRI-STATE function that may be used to

**RADIATION HARDENING**

PARAMETER	MIN	TYP	MAX	UNIT	COMMENT
TID	300	-	-	krad	Only validated on
SEL	60	-	-	MeVcm <sup>2</sup> /mg	original design
SEE performance	1E-13	-	-	Err/Bit/day	for a GEO orbit
TBC	-	-	-		ARQ-LVR002

More information about radiation hardening features and radiation test conditions is available under request.

**AVAILABLE OPTIONS**

PRODUCT	QUALITY LEVEL	PACKAGE	OPERATING TEMPERATURE	ORDERING NUMBER
ARQ-LVR002	Standard	16-FP	-55°C to 125°C	ARQ-LVR002-02
ARQ-LVR002	ESCC9000	16-FP	-55°C to 125°C	ARQ-LVR002-03

(\*) Other packaging options, including raw die format, are also available under request.

ARQ\_15601\_DSH\_002\_Drv

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**RADIATION HARDENING**

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
TID	300	-	-	krad	Only validated on
SEL	60	-	-	MeVcm <sup>2</sup> /mg	original design
SEE performance	1E-13	-	-	Err/Bit/day	for a GEO orbit
TBC	-	-	-		ARQ-LVR002

More information about radiation hardening features and radiation test conditions is available under request.

**AVAILABLE OPTIONS**

PRODUCT	QUALITY LEVEL	PACKAGE (*)	OPERATING TEMPERATURE	ORDERING NUMBER	VARIANT DETAIL	TRANSPORT MEDIA
ARQ-LVR002	Standard	16-pin CFP	-55°C to 125°C	ARQ-LVR002-01		50-pieces tray
ARQ-LVR002	ESCC9000	16-pin CFP	-55°C to 125°C	ARQ-LVR002-03		50-pieces tray

(\*) Other packaging options, including raw die format, are also available under request.

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Passion for Technology

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